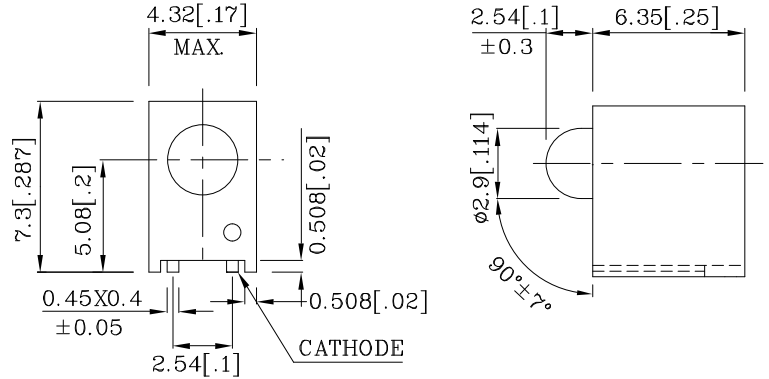


**Features**

- I.C. COMPATIBLE.
- BLACK CASE ENHANCES CONTRAST RATIO.
- WIDE VIEWING ANGLE.
- HIGH RELIABILITY LIFE MEASURED IN YEARS.
- HOUSING MATERIAL: PPA
- PACKAGE : 500PCS / REEL.
- HIGH TEMPERATURE RESISTANT HOUSING.
- HIGH GLASS TRANSITION TEMPERATURE EPOXY.
- RoHS COMPLIANT.



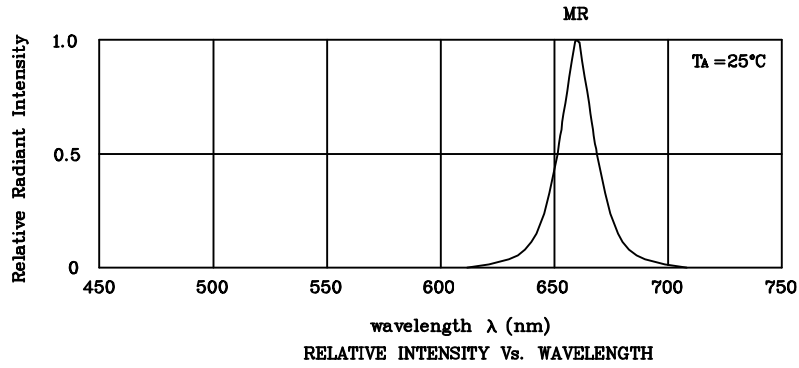
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
3. Specifications are subject to change without notice.

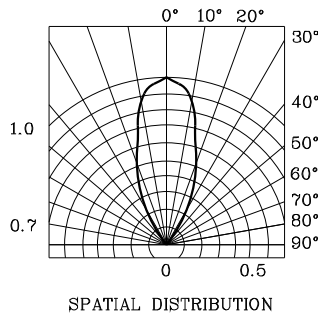
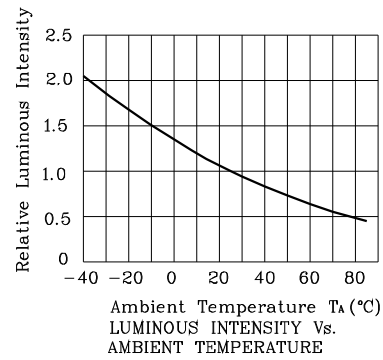
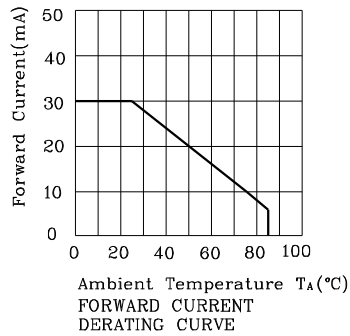
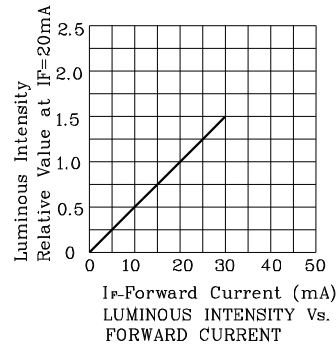
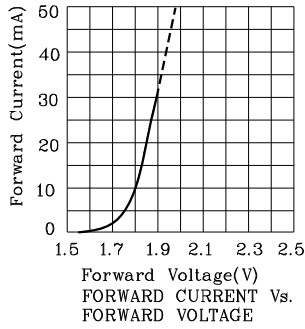
Absolute Maximum Ratings (TA=25°C)		MR (GaAlAs)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	155	mA
Power Dissipation	P <sub>T</sub>	75	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (TA=25°C)		MR (GaAlAs)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	V <sub>F</sub>	1.85	V
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	V <sub>F</sub>	2.5	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	uA
Wavelength Of Peak Emission (Typ.) (I <sub>F</sub> =20mA)	λ P	660	nm
Wavelength Of Dominant Emission (Typ.) (I <sub>F</sub> =20mA)	λ D	640	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	Δλ	20	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	45	pF

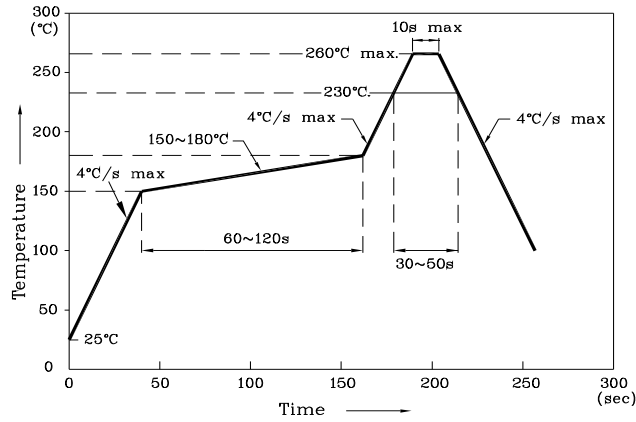
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I <sub>F</sub> =20mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XNK1LMRA147DSMD	Red	GaAlAs	Red Diffused	110	278	660	40°
Published Date : JAN 18,2008      Drawing No : XDSB1696      V1      Checked : B.L.LIU      P.1/4							



❖ MR



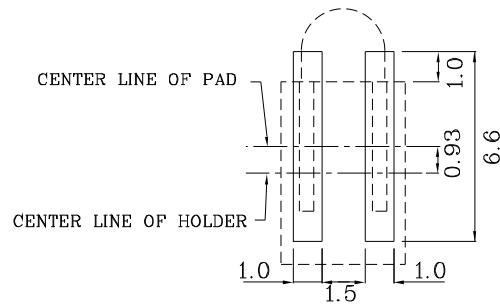
Reflow Soldering Profile For Lead-free SMT Process.



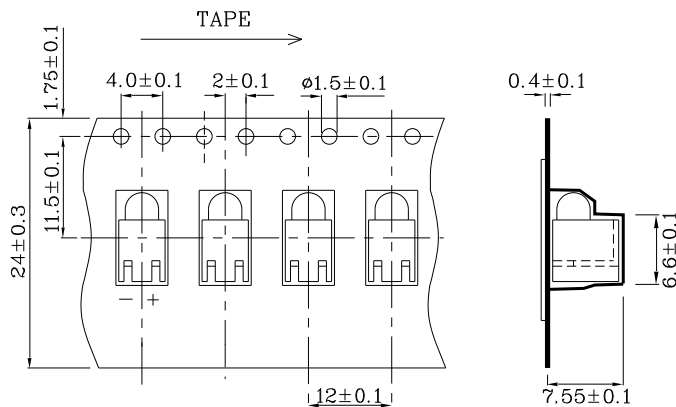
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units: mm ; Tolerance: ± 0.1)

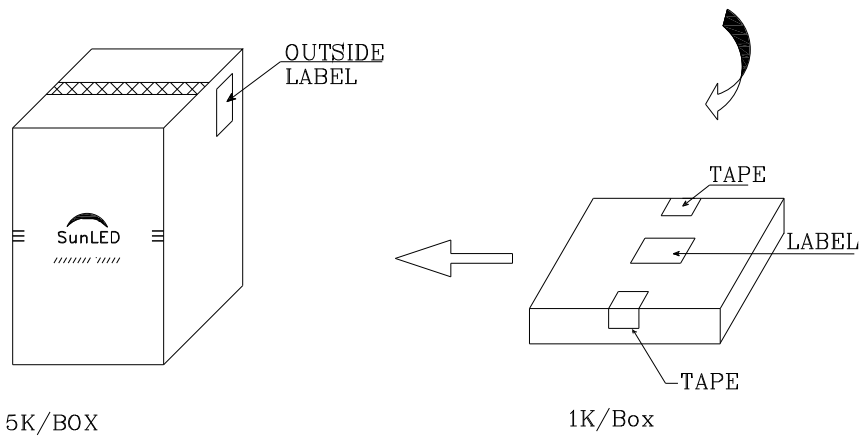
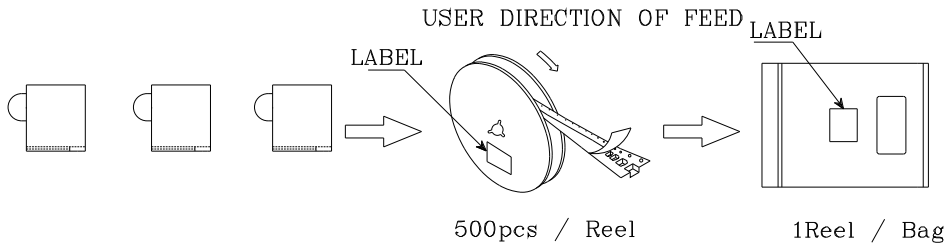



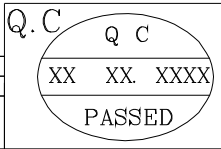


❖ Tape Specification (Units : mm)



**PACKING & LABEL SPECIFICATIONS**

**XNK1LMR147DSMD**

	
P/NO : XNK1Lxx147x	
	
QTY : 500 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	